

- Member of the Texas Instruments *Widebus*™ Family
- State-of-the-Art *EPIC-II B*™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) $< 1\text{ V}$ at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs ($-32\text{-mA } I_{OH}$, $64\text{-mA } I_{OL}$)
- Packaged in Plastic 300-mil Shrink Small-Outline (SSOP) Packages

description

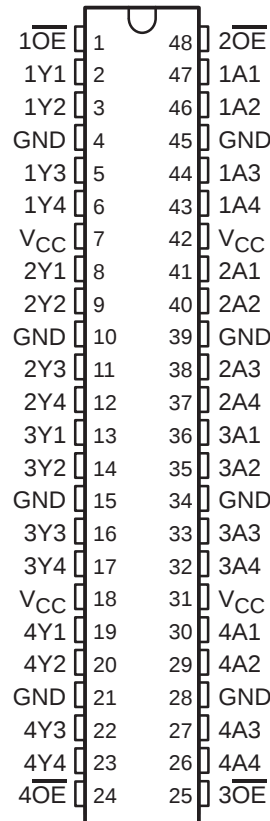
The SN74ABT16240 is a 16-bit buffer and line driver designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. This device provides inverting outputs and symmetrical active-low output-enable ($\overline{OE}$) inputs.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT16240 is available in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN74ABT16240 is characterized for operation from -40°C to 85°C .

DL PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each 4-bit buffer)

INPUTS		OUTPUT Y
$\overline{OE}$	A	
L	H	L
L	L	H
H	X	Z

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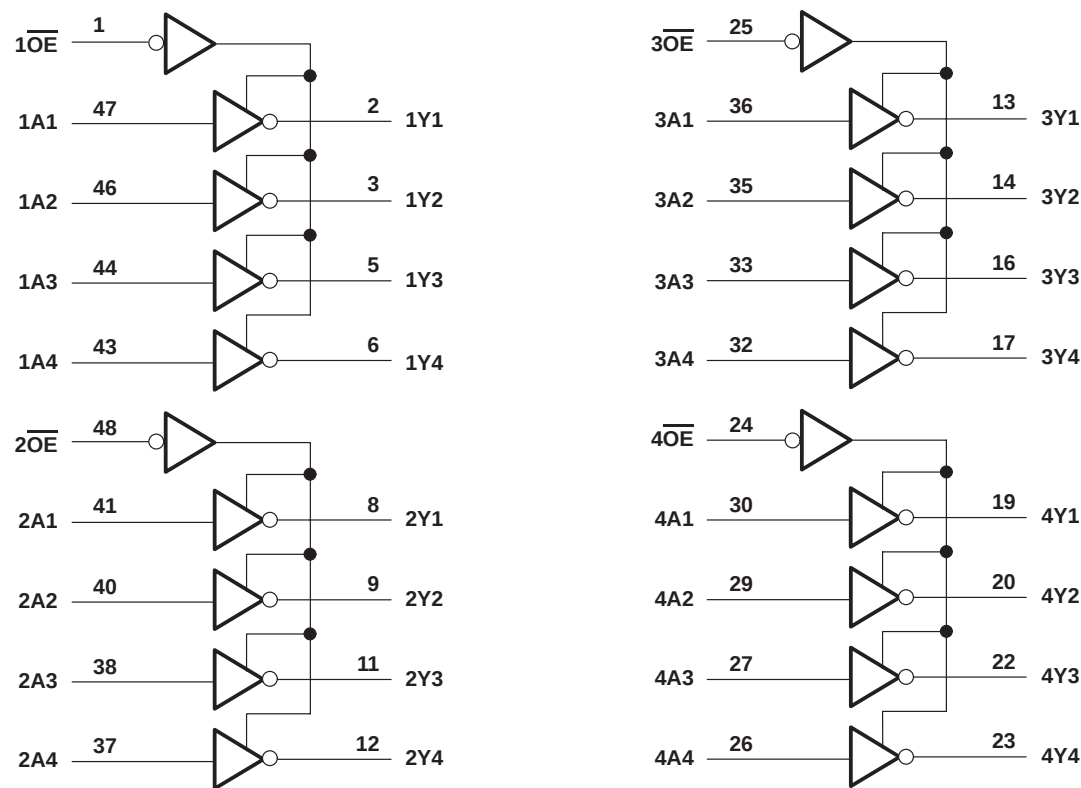
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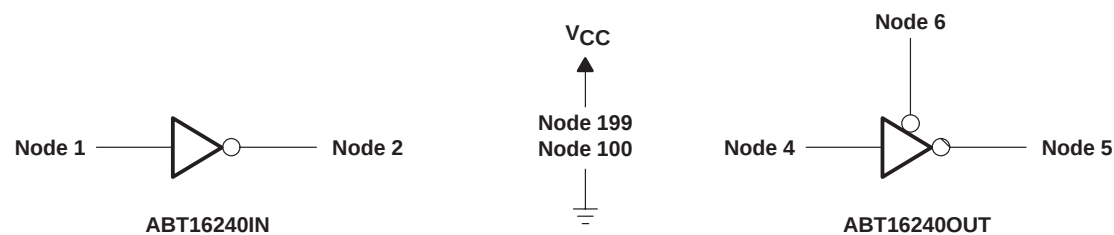
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logic diagram (positive logic)



SPICE block diagram



SPICE FUNCTION TABLE

NODE		OPERATION	NODE			OPERATION
1	2		4	5	6	
L	H	Input	L	H	L	Output
H	L	Input	H	L	L	Output
			X	Z	H	Hi-Z

SPICE netlist

```

*      ABT16240 SPICE I/O MODEL SUBCIRCUIT
*      ADVANCED BUS INTERFACE
*      ADVANCED SYSTEM LOGIC, TEXAS INSTRUMENTS
*
*      SUBCIRCUITS:  ABT16240IN, ABT16240OUT
*
*      PACKAGE PARASITICS
*      .LIB 'PKGS.LIB'      SSOP48
*
*      PROCESS MODELS
*      .LIB 'EPIC2B.LIB'  NOMINAL_L13
*      .LIB 'EPIC2B.LIB'  STRONG_L13
*      .LIB 'EPIC2B.LIB'  WEAK_L13
*
*  ABT16240 INPUT SUBCIRCUIT
*  NODES:
*
*      INPUT NODE
*      |      |
*      |      | INTERNAL OUTPUT NODE
*      |      | |      |
*      |      | |      | VCC
*      |      | |      | |
*      |      | |      | | GND
*      |      | |      | | |
*      |      | |      | | |
*
*  .SUBCKT ABT16240IN
*  X_PKGIN      1      1001
*  X_PKGVCC     199    1199
*  X_PKG GND    100    1100
*  XABT16240IN 1001    2      1199  1100
*  .ENDS ABT16240IN
*
*  ABT16240 OUTPUT SUBCIRCUIT
*  NODES:
*
*      INTERNAL INPUT NODE
*      |      |
*      |      | OUTPUT NODE
*      |      | |      |
*      |      | |      | INTERNAL OE NODE
*      |      | |      | |      |
*      |      | |      | |      | VCC
*      |      | |      | |      | |
*      |      | |      | |      | | GND
*      |      | |      | |      | | |
*      |      | |      | |      | | |
*
*  .SUBCKT ABT16240OUT
*  X_PKGOUT     5      1005
*  X_PKGVCC     199    1199
*  X_PKG GND    100    1100
*  XABT16240OUT 4      1005  6      1199  1100
*  .ENDS ABT16240OUT
*
*  .SUBCKT ABT16240__IN
*  XP1      502  504  506  599  500
*  XP2      509  502  599  599  PM
*  XP3      506  509  599  599  PM
*  XP4      508  500  599  599  PM
*  XN1      502  504  500  500  NM
*  XN2      509  502  500  500  NM
*  XN4      599  500  508  500  NM
*  QA       599  508  507
*  QB       599  507  506
*  Q_ESD1    501  500  500
*  Q_ESD     504  505  500
*  XR1       506  507  507  507  RMOS
*  RESD1     501  504
*  RESD2     505  500
*  CBP       501  500
*  CL        502  500
*  .ENDS ABT16240__IN
*
*  .SUBCKT ABT16240__OUT
*  XP1      605  603  699  699  PM
*  XP4      601  603  621  699  PM
*  XP5      613  601  605  699  PM
*  XP10     618  603  699  699  PM
*  XP11     607  612  605  699  PM
*  XN1      607  601  608  600  NM
*
*  WP=200U      LP=0.8U
*  WP=20U       LP=0.8U
*  WP=85U       LP=0.8U
*  WP=50U       LP=0.8U
*  WN=220U      LN=0.8U
*  WN=20U       LN=0.8U
*  WN=20U       LN=0.8U
*  Q2_NPN       10
*  Q5_NPN       60
*  Q7_NPN       200
*  Q5_NPN       46
*  WR=4U        RES=6K
*  50
*  1K
*  0.3P
*  0.2P
*
*  WP=200U      LP=0.8U
*  WP=40U       LP=0.8U
*  WP=30U       LP=0.8U
*  WP=50U       LP=0.8U
*  WP=60U       LP=0.8U
*  WN=100U      LN=0.8U

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SN74ABT16240
16-BIT BUFFER/DRIVER
WITH 3-STATE OUTPUTS

SCBS346 – MAY 1994

SPICE I/O MODEL

SPICE netlist (continued)

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XN2      606  619  607  600  NM      WN=50U      LN=0.8U
XN3      608  609  600  600  NM      WN=25U      LN=0.8U
XN4      608  603  600  600  NM      WN=80U      LN=0.8U
XN6      613  603  600  600  NM      WN=25U      LN=0.8U
XN7      602  621  600  600  NM      WN=100U     LN=0.8U
XN8      621  603  600  600  NM      WN=10U      LN=0.8U
XN9      601  622  621  600  NM      WN=20U      LN=0.8U
XN10     619  619  620  600  NM      WN=25U      LN=0.8U
XN11     620  604  602  600  NM      WN=25U      LN=0.8U
XN12     613  601  600  600  NM      WN=40U      LN=0.8U
QM1      616  615  602      Q9_NPN      200
QM2      602  608  600      Q11_NPN     600
QM3      614  613  615      Q4_NPN      15
QD4      614  614  616      Q2_NPN      8
QDR1     615  615  613      Q2_NPN      8
D1       613  614      D1_GDS     156
D2       699  617      D9_GSD     4700
XR1      606  605  605  605  RMOS     WR=6U      RES=1K
XR2      607  606  606  606  RMOS     WR=4U      RES=3K
XR3      614  605  605  605  RMOS     WR=6U      RES=1K
R4       616  617      10
XR10     619  618  618  618  RMOS     WR=3U      RES=20K
XPVREF   670  603  699  699  PM       WP=50U     LP=0.8U
XNVREF   671  671  600  600  NM       WN=30U     LN=0.8U
XRVREF1  604  670  670  670  RMOS     WR=3U      RES=20K
XRVREF2  671  604  604  604  RMOS     WR=3U      RES=1.5K
XNCLAMP  673  612  674  600  NM       WN=250U    LN=0.8U
DCLAMP1  608  673      D6_GSD     800
DCLAMP2  674  602      D6_GSD     800
XPNOR1   675  609  699  699  PM       WP=30U     LP=0.8U
XPNOR2   612  611  675  699  PM       WP=30U     LP=0.8U
XNNOR1   612  611  600  600  NM       WN=6U      LN=0.8U
XNNOR2   612  609  600  600  NM       WN=6U      LN=0.8U
XP_INV1  609  601  699  699  PM       WP=20U     LP=0.8U
XN_INV1  609  601  600  600  NM       WN=10U     LN=0.8U
XP_INV2  622  603  699  699  PM       WP=15U     LP=0.8U
XN_INV2  622  603  600  600  NM       WN=5U      LN=0.8U
XP_INV3  610  603  699  699  PM       WP=4U      LP=0.8U
XN_INV3  610  603  600  600  NM       WN=4U      LN=0.8U
XP_INV4  611  610  699  699  PM       WP=4U      LP=0.8U
XN_INV4  611  610  600  600  NM       WN=4U      LN=0.8U
CBP      602  600      0.3P
.ENDS ABT16240__OUT
*
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